





Parameter	Rating	Units
Load Voltage	60	V
Load Current	1	Α
Max On-resistance	0.4	Ω

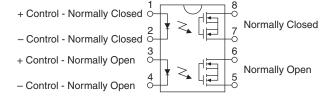
Features

- 3750V_{rms} Input/Output Isolation
- Small 8-Pin Package
- Low Drive Power Requirements (TTL/CMOS Compatible)
- Arc-Free With No Snubbing Circuits
- No EMI/RFI Generation
- · Machine Insertable, Wave Solderable
- Surface Mount Version
- Tape & Reel available

Applications

- Telecommunications
- Instrumentation
 - Multiplexers
 - Data Acquisition
 - Electronic Switching
 - I/O Subsystems
 - Utility Meters (gas, oil, electric and water)
- Medical Equipment-Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

Pin Configuration



Description

LBA716 is a 60V, 1A, 0.4Ω dual Solid State Relay integrating independent normally open (1-Form-A) and normally closed (1-Form-B) relays into a single package. It features a superior combination of low on-resistance and enhanced peak load current (5A max.) handling capability.

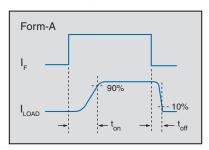
Approvals

- UL Recognized Component: File # E76270
- CSA Certified Component: Certificate # 1175739
- EN/IEC 60950-1 Certified Component TUV Certificate B 09 07 49410 004

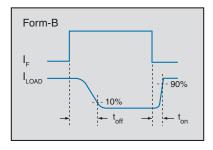
Ordering Information

Part #	Description
LBA716	8-Pin DIP (50/Tube)
LBA716S	8-Pin Surface Mount (50/Tube)
LBA716STR	8-Pin Surface Mount (1000/Reel)

Switching Characteristics of Normally Open Devices



Switching Characteristics of Normally Closed Devices











Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units	
Blocking Voltage	60	V _P	
Reverse Input Voltage	5	V	
Input Control Current	50	mA	
Peak (10ms)	1	Α	
Input Power Dissipation ¹	150	mW	
Total Power Dissipation ²	800	mW	
Isolation Voltage, Input to Output	3750	V _{rms}	
Operational Temperature	-40 to +85	°C	
Storage Temperature	-40 to +125	°C	

excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Absolute Maximum Ratings are stress ratings. Stresses in

Electrical Characteristics @ 25°C

Parameter	Conditions	Symbol	Min	Тур	Max	Units
Characte	ristics: Form-A (No	rmally Op	en)			
Load Current						
Continuous	-	IL	-	-	1	A
Peak	t ≤ 10ms	I _{I PK}	-	-	5	
On-resistance	I _I =1A	R _{ON}	-	0.21	0.4	Ω
Off-State Leakage Current	V ₁ =60V	I _{LEAK}	-	-	1	μΑ
Output Capacitance	50V, f=1MHz	C _{OUT}	-	105	-	pF
Switching Speeds						
Turn-On	1 5 A 1/ 401/	t _{ON}	-	0.7	5	ms
Turn-Off	I _F =5mA, V _L =10V	t _{OFF}	-	0.09	5	
Input Control Current	I _L =1A	I _F	-	-	2	mA
Input Dropout Current	-	I _F	0.1	-	-	mA
Character	istics: Form-B (Nor	mally Clos	sed)			
Load Current						
Continuous	-	IL	-	-	0.5	A
Peak	t ≤ 10ms	I _{LPK}	-	-	1.2	
On-resistance	I _I =0.5A	R _{ON}	-	1.63	2	Ω
Off-State Leakage Current	V _L =60V, I _F =5mA	I _{LEAK}	-	-	1	μΑ
Output Capacitance	I _F =5mA, 50V, f=1MHz	C _{OUT}	-	280	-	pF
Switching Speeds						
Turn-On	I -5m/ \/ -10\/	t _{ON}	-	0.58	5	me
Turn-Off	I _F =5mA, V _L =10V	t _{OFF}	-	0.76	5	ms
Input Control Current	-	I _F	-	-	2	mA
Input Dropout Current	I _L =0.5A	I _F	0.1	-	-	mA
Common Ch	naracteristics: Forn	n-A and F	orm-B			
Input Voltage Drop	I _F =5mA	V_{F}	0.9	1.2	1.4	V
Reverse Input Current	V _R =5V	I _R	-	-	10	μΑ
Capacitance, Input to Output	-	C _{I/O}	-	3	-	pF

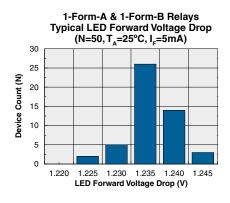
^{*}NOTE: If both poles operate simultaneously load current must be derated so as not to exceed the package power dissipation value.

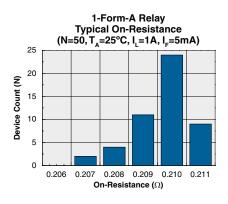
¹ Derate Linearly 1.33 mW/°C

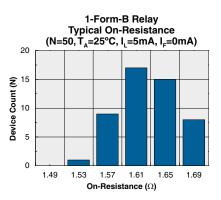
² Derate Linearly 6.67 mW/°C

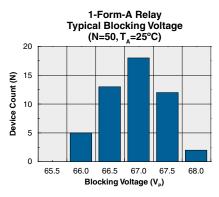


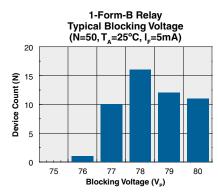
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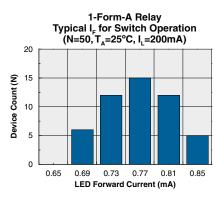


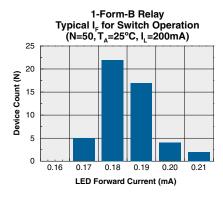


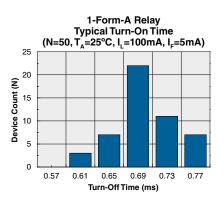


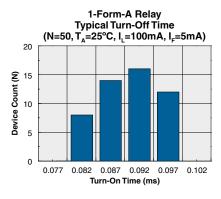


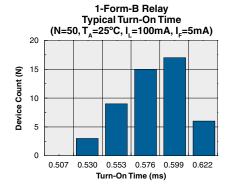


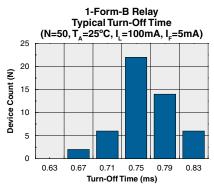








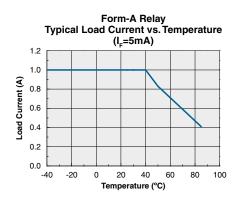


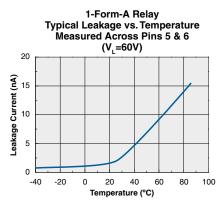


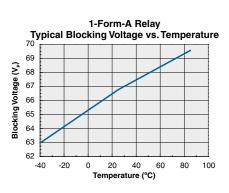
^{*}The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

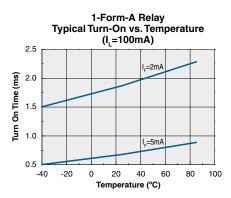


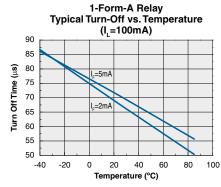
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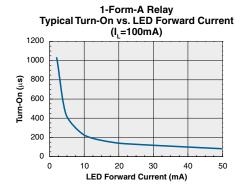


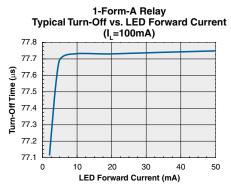


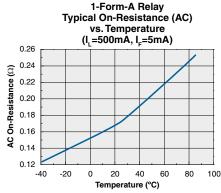


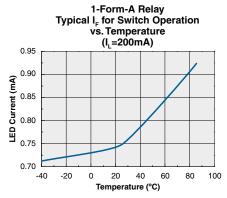


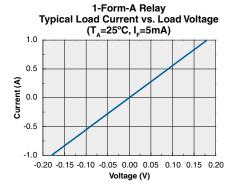


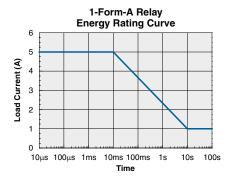








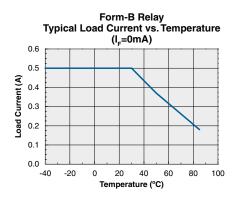


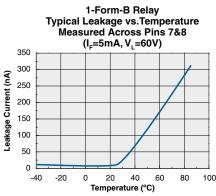


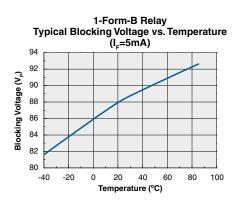
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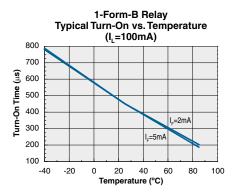


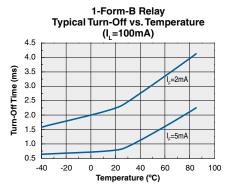
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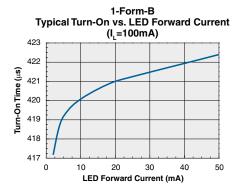


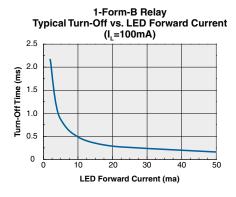


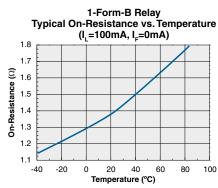


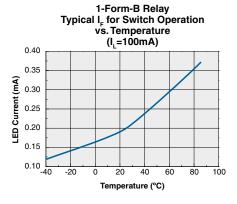


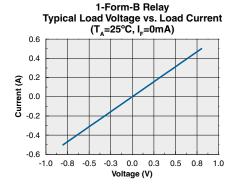


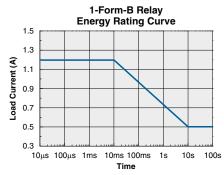












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Manufacturing Information

Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingression. Clare classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, IPC/JEDEC J-STD-020, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product is rated Moisture Sensitivity Level 1 (MSL 1), and should be handled according to the requirements of the latest version of the joint industry standard IPC/JEDEC J-STD-033.

ESD Sensitivity



This product is ESD Sensitive, and should be handled according to the industry standard JESD-625.

Reflow Profile

This product has a maximum body temperature rating of 250°C for a maximum of 30 seconds. All other guidelines of J-STD-020 must be observed.

Board Wash

Clare recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable. Since Clare employs the use of silicone coating as an optical waveguide in many of its optically isolated products, the use of a short drying bake could be necessary if a wash is used after solder reflow processes. Chlorine- or Fluorinebased solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.

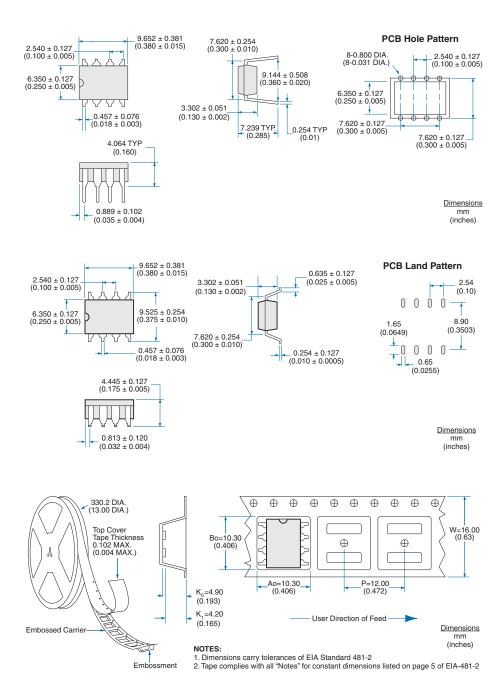








Mechanical Dimensions



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